



- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

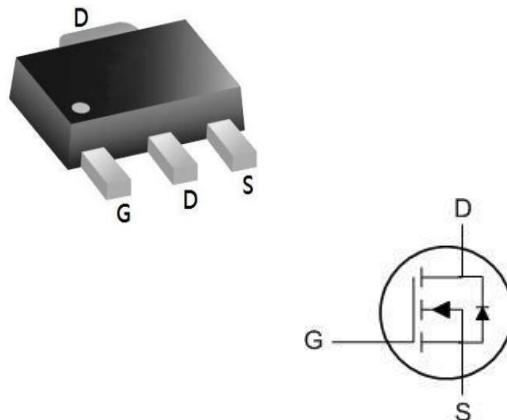
BVDSS	RDS(ON)	ID
60V	40mΩ	10 A

### Description

The XXW10N06Q is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XXW10N06Q meet the RoHS and Green Product requirement with full function reliability approved.

### SOT89-3L Pin Configuration



### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ\text{C}$	10	A
		$T_c = 100^\circ\text{C}$	6.8	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		30	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		6.3	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ\text{C}$	4	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		63	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

**N-Ch 60V Fast Switching MOSFETs**
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1	1.6	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=15\text{A}$	-	40	49	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	-	45	63	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	825	-	pF
$C_{oss}$	Output Capacitance		-	49	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	41	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30\text{V}$ , $I_D=4.5\text{A}$ , $V_{GS}=10\text{V}$	-	14	-	nC
$Q_{gs}$	Gate-Source Charge		-	2.9	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5.2	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$ , $I_D=2\text{A}$ , $R_L=6.7\Omega$ , $R_G=3\Omega$ , $V_{GS}=10\text{V}$	-	5	-	ns
$t_r$	Turn-on Rise Time		-	2.6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	16.1	-	ns
$t_f$	Turn-off Fall Time		-	2.3	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	10	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	30	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=15\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$ , $I_F=15\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	35	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	53	-	nC

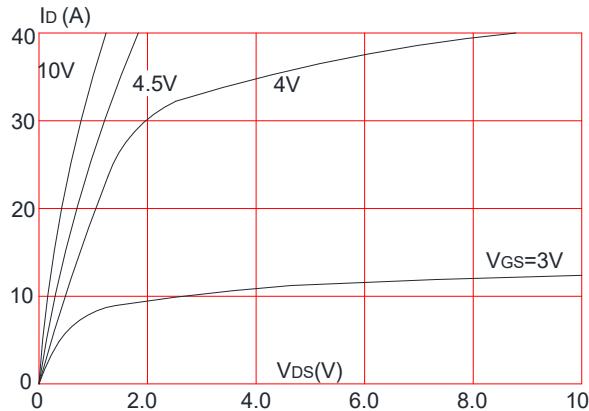
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=6.1\text{A}$

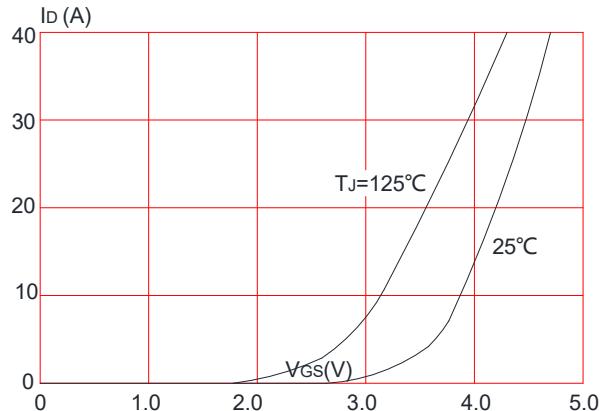
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

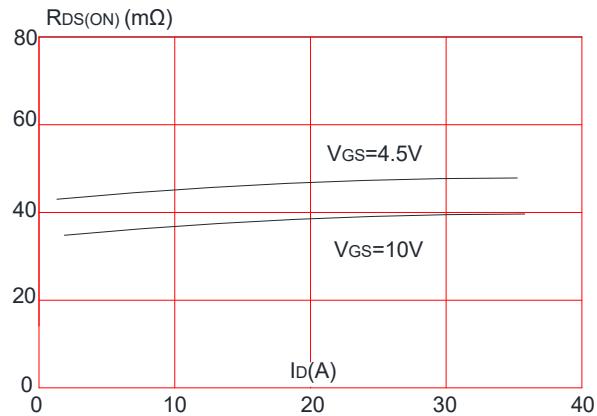
**Figure1:** Output Characteristics



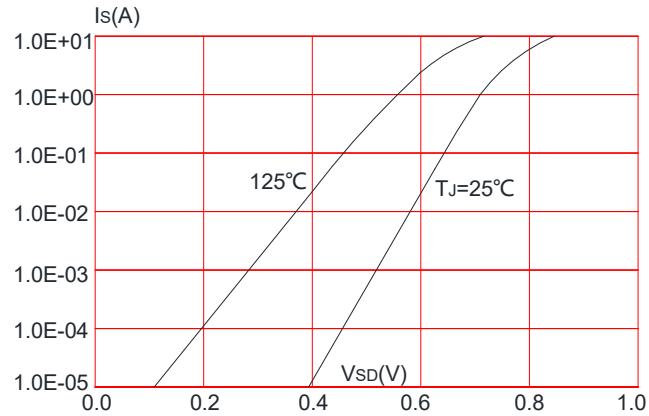
**Figure 2:** Typical Transfer Characteristics



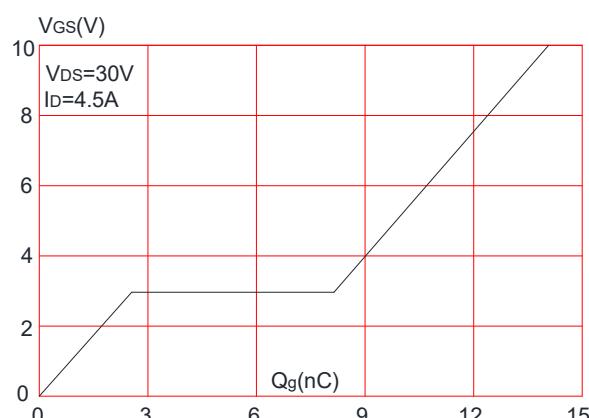
**Figure 3:** On-resistance vs. Drain Current



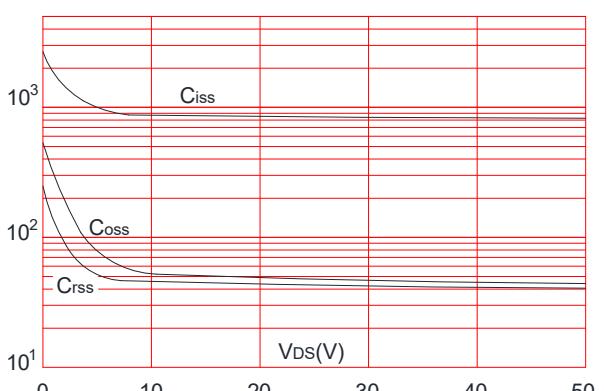
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

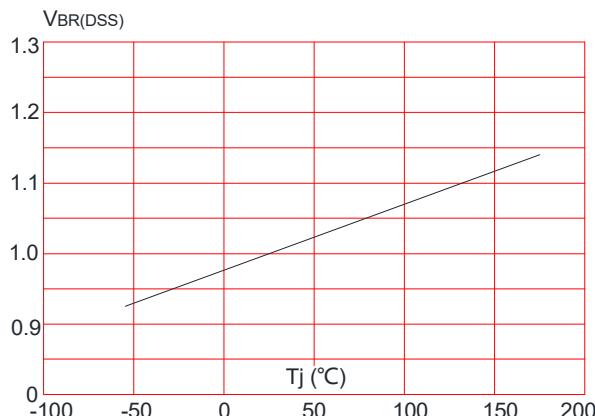


**Figure 6:** Capacitance Characteristics

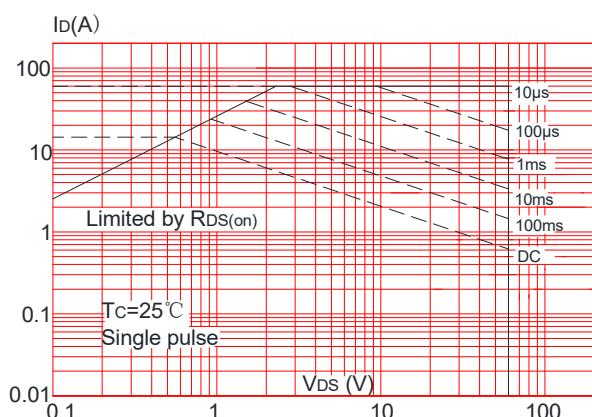


**N-Ch 60V Fast Switching MOSFETs**

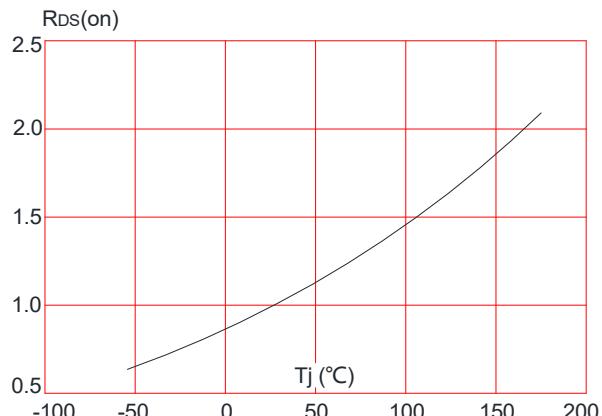
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



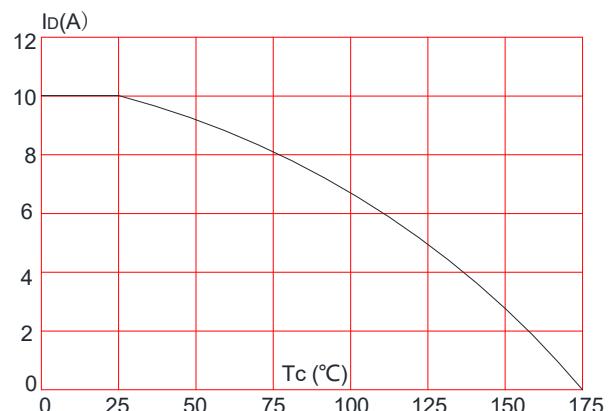
**Figure 9:** Maximum Safe Operating Area



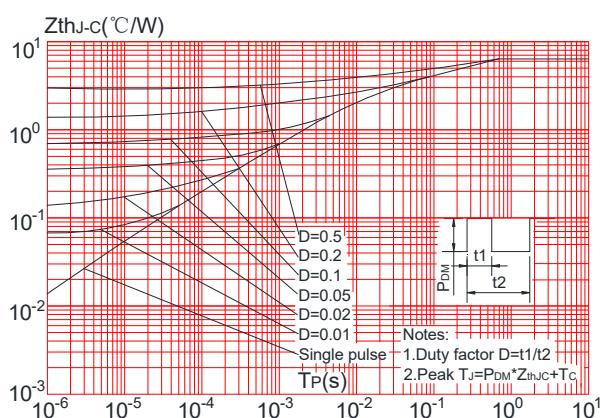
**Figure 8:** Normalized on Resistance vs. Junction Temperature

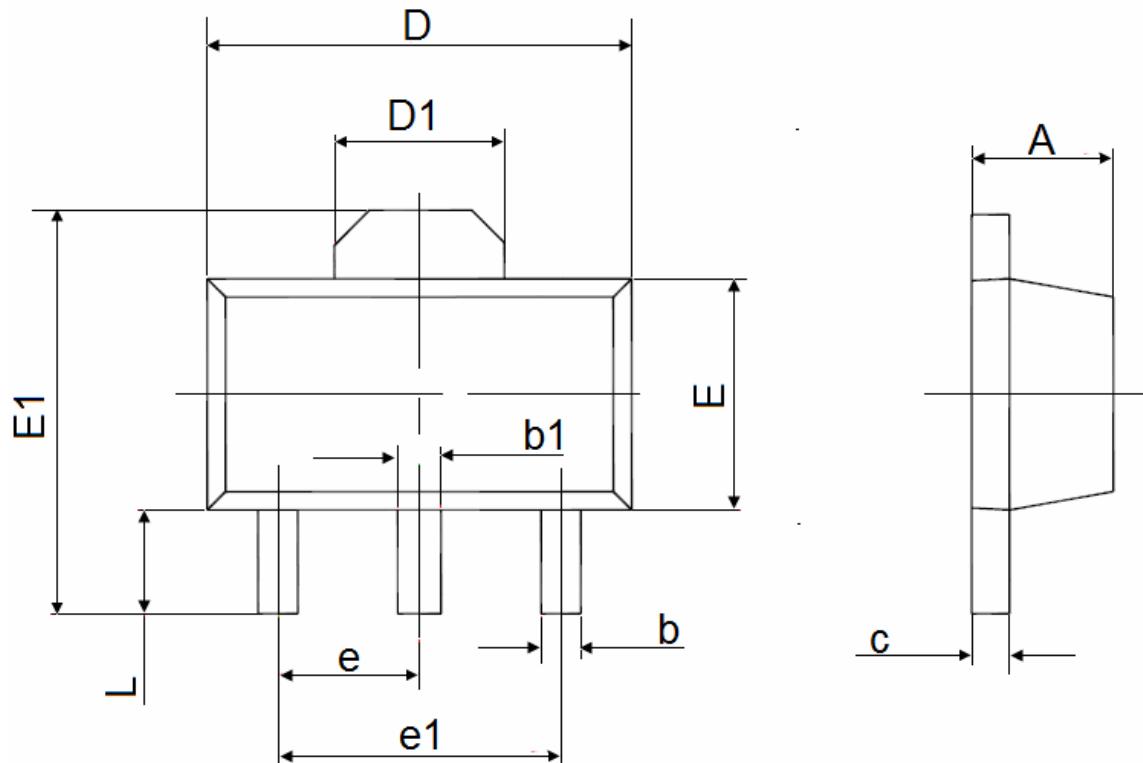


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**SOT-89-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047